

# E4MS018120J2

## Automotive Silicon Carbide Power MOSFET



### Features

- Industry compatible drive voltage 15 V ...18 V/-4 V ...0 V
- Low  $R_{DS(on)}$  at high operating temperatures
- Improved device capacitance ratio ( $C_{iss}/C_{rss}$ )
- Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

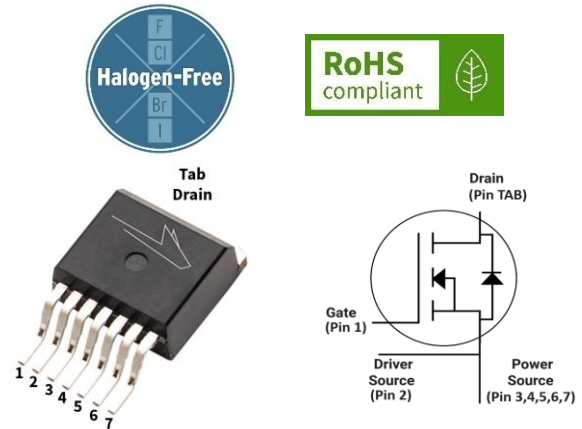
### Benefits

- Higher efficiency with lower switching losses and EMI
- Faster switching operation enabling high power density
- Enables system level price performance optimization
- Reduction in system level cooling requirements

### Typical Applications

- Onboard charger
- High voltage DC/DC converters
- HVAC compressors
- Battery management systems

### Package



| Orderable Part Number | Package Type | Marking      |
|-----------------------|--------------|--------------|
| E4MS018120J2-TR       | TO-263-7 XL  | E4MS018120J2 |

### Absolute Maximum Ratings

Stress beyond those listed under absolute maximum ratings may damage the device.

| Symbol         | Parameter                                  | Min. | Max. | Unit             | Conditions                                                                                    | Note   |
|----------------|--------------------------------------------|------|------|------------------|-----------------------------------------------------------------------------------------------|--------|
| $V_{DS(max)}$  | Drain-Source Voltage                       |      | 1200 | V                |                                                                                               |        |
| $V_{GS(max)}$  | Maximum Gate – Source Voltage (Transient)  | -10  | +23  |                  |                                                                                               | Note 1 |
| $I_D$          | DC Continuous Drain Current                |      | 116  | A                | $V_{GS} = 18\text{ V}, T_c = 25\text{ }^\circ\text{C}, T_J \leq 175\text{ }^\circ\text{C}$    | Note 2 |
|                |                                            |      | 82   |                  | $V_{GS} = 18\text{ V}, T_c = 100\text{ }^\circ\text{C}, T_J \leq 175\text{ }^\circ\text{C}$   |        |
| $I_{DM}$       | Pulsed Drain Current                       |      | 369  |                  | $V_{GS} = 18\text{ V}, T_c = 25\text{ }^\circ\text{C}, t_{pmax} \text{ limited by } T_{Jmax}$ |        |
| $P_D$          | Power Dissipation                          |      | 454  | W                | $T_c = 25\text{ }^\circ\text{C}, T_J = 175\text{ }^\circ\text{C}$                             | Note 3 |
| $T_J, T_{stg}$ | Operating Junction and Storage Temperature | -55  | +175 | $^\circ\text{C}$ |                                                                                               |        |
| $T_L$          | Solder Temperature                         |      | 260  |                  | According to JEDEC J-STD-020                                                                  |        |

Note (1): Refer to AN PRD-09634

Note (2): Current limit calculated by  $I_{D(max)} = \sqrt{(P_D / R_{DS(typ)}(T_{J(max)}, I_{D(max)}))}$

Note (3):  $P_D = (T_J - T_c) / R_{th(JC, Max)}$



## Electrical Characteristics ( $T_c = 25\text{ }^\circ\text{C}$ unless otherwise specified)

| Symbol             | Parameter                                                                                                           | Min. | Typ.       | Max. | Unit          | Test Conditions                                                                                                                                                                                 | Note               |
|--------------------|---------------------------------------------------------------------------------------------------------------------|------|------------|------|---------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------|
| $V_{(BR)DSS}$      | Drain – Source Breakdown Voltage                                                                                    | 1200 |            |      | V             | $V_{GS} = 0\text{ V}$ , $I_b = 100\text{ }\mu\text{A}$                                                                                                                                          |                    |
| $V_{GS(th)}$       | Gate Threshold Voltage                                                                                              | 2.0  | 2.6        | 3.9  | V             | $V_{DS} = V_{GS}$ , $I_b = 14.5\text{ mA}$                                                                                                                                                      | Fig. 11,<br>Note 1 |
|                    |                                                                                                                     |      | 2.0        |      | V             | $V_{DS} = V_{GS}$ , $I_b = 14.5\text{ mA}$ , $T_J = 175\text{ }^\circ\text{C}$                                                                                                                  |                    |
| $I_{DSS}$          | Zero Gate Voltage Drain Current                                                                                     |      | 1          | 50   | $\mu\text{A}$ | $V_{DS} = 1200\text{ V}$ , $V_{GS} = 0\text{ V}$                                                                                                                                                |                    |
| $I_{GSS}$          | Gate-Source Leakage Current                                                                                         |      | 10         | 250  | nA            | $V_{GS} = 18\text{ V}$ , $V_{DS} = 0\text{ V}$                                                                                                                                                  |                    |
| $V_{GS(op)}$       | Recommended Turn on Gate-Source Voltage                                                                             |      | +15...+18  |      | V             |                                                                                                                                                                                                 | Note 4             |
|                    | Recommended Turn off Gate-Source Voltage                                                                            |      | -4...0     |      |               |                                                                                                                                                                                                 |                    |
| $R_{DS(on)}$       | Drain-Source On-State Resistance                                                                                    |      | 18         | 23.4 | m $\Omega$    | $V_{GS} = 18\text{ V}$ , $I_b = 52.7\text{ A}$                                                                                                                                                  | Fig. 4, 5,<br>6    |
|                    |                                                                                                                     |      | 33.8       |      |               | $V_{GS} = 18\text{ V}$ , $I_b = 52.7\text{ A}$ , $T_J = 175\text{ }^\circ\text{C}$                                                                                                              |                    |
|                    |                                                                                                                     |      | 21         |      |               | $V_{GS} = 15\text{ V}$ , $I_b = 52.7\text{ A}$                                                                                                                                                  |                    |
| $g_{fs}$           | Transconductance                                                                                                    |      | 39         |      | S             | $V_{DS} = 20\text{ V}$ , $I_b = 52.7\text{ A}$                                                                                                                                                  | Fig. 7             |
|                    |                                                                                                                     |      | 38         |      |               | $V_{DS} = 20\text{ V}$ , $I_b = 52.7\text{ A}$ , $T_J = 175\text{ }^\circ\text{C}$                                                                                                              |                    |
| $R_{DS(on)Tempco}$ | On Resistance Temperature Coefficient                                                                               |      | 1.88       |      |               | $V_{GS} = 18\text{ V}$ , $I_b = 52.7\text{ A}$                                                                                                                                                  | Note 5             |
| $C_{iss}$          | Input Capacitance                                                                                                   |      | 4105       |      | pF            | $V_{GS} = 0\text{ V}$ , $V_{DS} = 1000\text{ V}$<br>$f = 100\text{ kHz}$<br>$V_{AC} = 25\text{ mV}$                                                                                             | Fig. 17,<br>18     |
| $C_{oss}$          | Output Capacitance                                                                                                  |      | 148        |      |               |                                                                                                                                                                                                 |                    |
| $C_{rss}$          | Reverse Transfer Capacitance                                                                                        |      | 6.5        |      |               |                                                                                                                                                                                                 |                    |
| $C_{iss}/C_{rss}$  | Capacitance Ratio                                                                                                   |      | 630        |      |               |                                                                                                                                                                                                 | Note 6             |
| $E_{oss}$          | Coss Stored Energy                                                                                                  |      | 96         |      | $\mu\text{J}$ |                                                                                                                                                                                                 | Fig. 16            |
| $C_{o(er)}$        | Effective Output Capacitance (Energy Related)                                                                       |      | 215        |      | pF            | $V_{GS} = 0\text{ V}$ , $V_{DS} = 0\text{ V} \dots 800\text{ V}$                                                                                                                                | Note 7             |
| $C_{o(tr)}$        | Effective Output Capacitance (Time Related)                                                                         |      | 350        |      |               |                                                                                                                                                                                                 |                    |
| $E_{on}$           | Turn-On Switching Energy (Body Diode FWD)<br>$T_J = 25\text{ }^\circ\text{C}$<br>$T_J = 175\text{ }^\circ\text{C}$  |      | 347<br>343 |      | $\mu\text{J}$ | $V_{DS} = 800\text{ V}$ , $V_{GS} = -4\text{ V} / 18\text{ V}$ ,<br>$I_b = 52.7\text{ A}$ , $R_{G(ext)} = 2\text{ }\Omega$ , $L_o = 14\text{ nH}$                                               | Fig. 25,<br>27, 29 |
| $E_{off}$          | Turn-Off Switching Energy (Body Diode FWD)<br>$T_J = 25\text{ }^\circ\text{C}$<br>$T_J = 175\text{ }^\circ\text{C}$ |      | 133<br>130 |      |               |                                                                                                                                                                                                 | Fig. 25,<br>28, 29 |
| $t_{d(on)}$        | Turn-On Delay Time                                                                                                  |      | 14         |      | ns            | $V_{DS} = 800\text{ V}$ , $V_{GS} = -4\text{ V} / 18\text{ V}$ ,<br>$I_b = 52.7\text{ A}$ , $R_{G(ext)} = 2\text{ }\Omega$ , $L_o = 14\text{ nH}$<br>Timing relative to $I_{DS}$ Inductive load | Fig. 26,<br>27, 29 |
| $t_r$              | Rise Time                                                                                                           |      | 5          |      |               |                                                                                                                                                                                                 | Fig. 26,<br>28, 29 |
| $t_{d(off)}$       | Turn-Off Delay Time                                                                                                 |      | 34         |      |               |                                                                                                                                                                                                 |                    |
| $t_f$              | Fall Time                                                                                                           |      | 12         |      |               |                                                                                                                                                                                                 |                    |
| $R_{G(int)}$       | Internal Gate Resistance                                                                                            |      | 1.2        |      | $\Omega$      | $f = 1\text{ MHz}$                                                                                                                                                                              |                    |
| $Q_{gs}$           | Gate to Source Charge                                                                                               |      | 47         |      | nC            | $V_{DS} = 800\text{ V}$ , $V_{GS} = -4\text{ V} / 18\text{ V}$<br>$I_b = 52.7\text{ A}$                                                                                                         | Fig. 12            |
| $Q_{gd}$           | Gate to Drain Charge                                                                                                |      | 50         |      |               |                                                                                                                                                                                                 |                    |
| $Q_g$              | Total Gate Charge                                                                                                   |      | 172        |      |               |                                                                                                                                                                                                 |                    |

Note (4): Refer to [AN PRD-08999](#).

Note (5):  $R_{DS(on)Tempco}$  refers to  $R_{DS(on)}$  at  $175\text{ }^\circ\text{C}$  /  $R_{DS(on)}$  at  $25\text{ }^\circ\text{C}$ . This is a E4MS 1200 V product family value.

Note (6): Capacitance ratio is a FOM for partial turn-on immunity [AN PRD-06933](#). This is a E4MS 1200 V product family value.

Note (7):  $C_{o(er)}$ , a lumped capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 800 V.

$C_{o(tr)}$ , a lumped capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 800 V.



### Reverse Diode Characteristics ( $T_c = 25^\circ\text{C}$ unless otherwise specified)

| Symbol    | Parameter                                                                        | Typ.       | Max. | Unit          | Test Conditions                                                                                                                       | Note          |
|-----------|----------------------------------------------------------------------------------|------------|------|---------------|---------------------------------------------------------------------------------------------------------------------------------------|---------------|
| $V_{SD}$  | Diode Forward Voltage                                                            | 5.1        |      | V             | $V_{GS} = -4\text{ V}, I_{SD} = 26.4\text{ A}, T_J = 25^\circ\text{C}$                                                                | Fig. 8, 9, 10 |
|           |                                                                                  | 4.5        |      |               | $V_{GS} = -4\text{ V}, I_{SD} = 26.4\text{ A}, T_J = 175^\circ\text{C}$                                                               |               |
| $I_S$     | Continuous Diode Forward Current                                                 |            | 71   | A             | $V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$                                                                                        |               |
| $I_{SM}$  | Diode Pulse Current                                                              |            | 369  |               | $V_{GS} = -4\text{ V}$ , pulse width $t_p$ limited by $T_{Jmax}$                                                                      |               |
| $t_{rr}$  | Reverse Recovery Time                                                            | 17         |      | ns            | $V_{GS} = -4\text{ V}, I_{SD} = 52.7\text{ A}, V_R = 800\text{ V}$ ,<br>$T_J = 175^\circ\text{C}, di/dt = 16694\text{ A}/\mu\text{s}$ | Fig. 30       |
| $Q_{rr}$  | Reverse Recovery Charge                                                          | 1099       |      | nC            |                                                                                                                                       |               |
| $I_{RRM}$ | Peak Reverse Recovery Current                                                    | 104        |      | A             |                                                                                                                                       |               |
| $E_{RR}$  | Reverse Recovery Energy<br>$T_J = 25^\circ\text{C}$<br>$T_J = 175^\circ\text{C}$ | 439<br>720 |      | $\mu\text{J}$ | $V_{DS} = 800\text{ V}, I_{DS} = 52.7\text{ A}$ ,<br>$V_{GS} = -4\text{ V} / 18\text{ V}, R_{G(ext)} = 2\ \Omega, L_G = 14\text{ nH}$ |               |

### Thermal Characteristics

| Symbol          | Parameter                                | Typ. | Max. | Unit                      | Test Conditions | Note |
|-----------------|------------------------------------------|------|------|---------------------------|-----------------|------|
| $R_{\theta JC}$ | Thermal Resistance from Junction to Case | 0.25 | 0.33 | $^\circ\text{C}/\text{W}$ |                 |      |

## Typical Performance

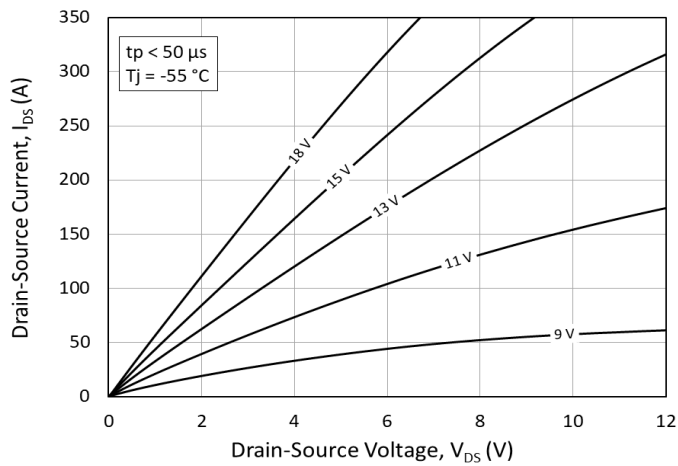
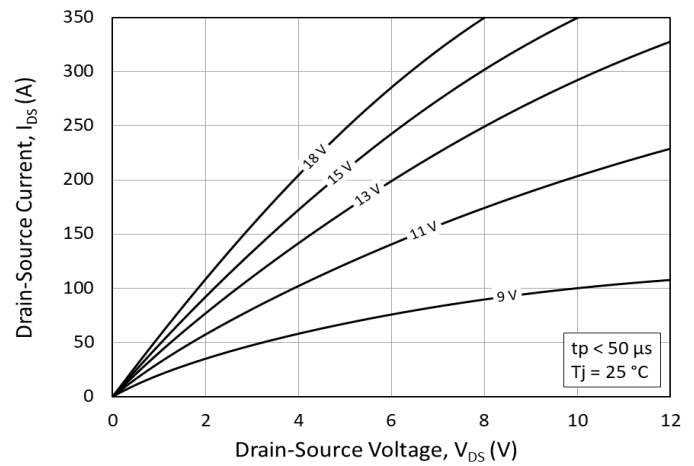
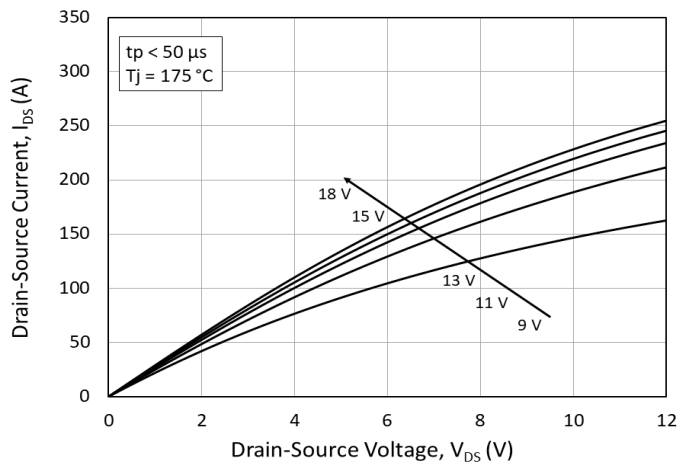
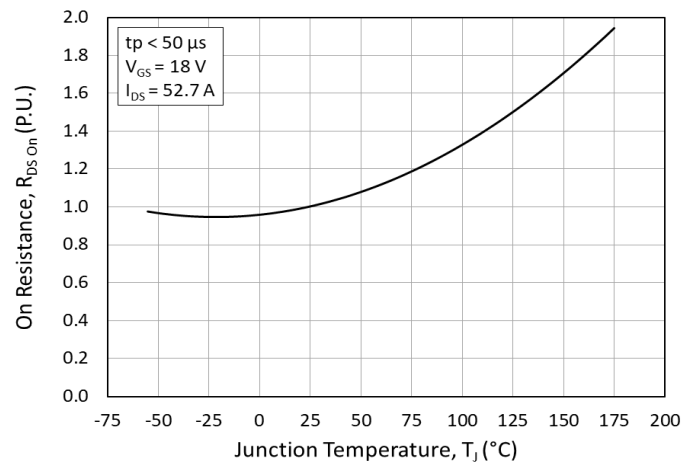
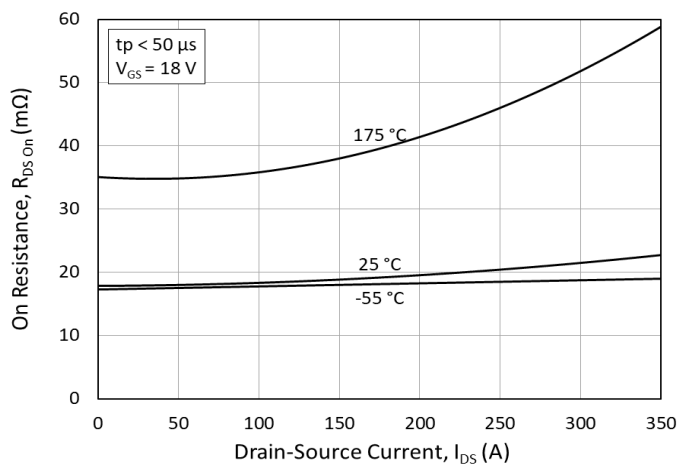
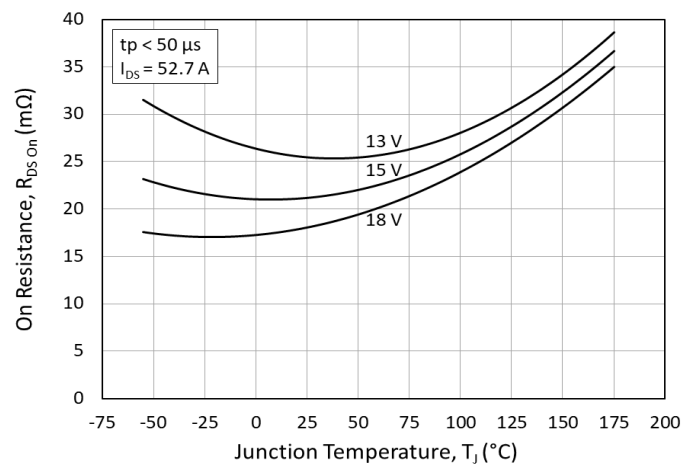
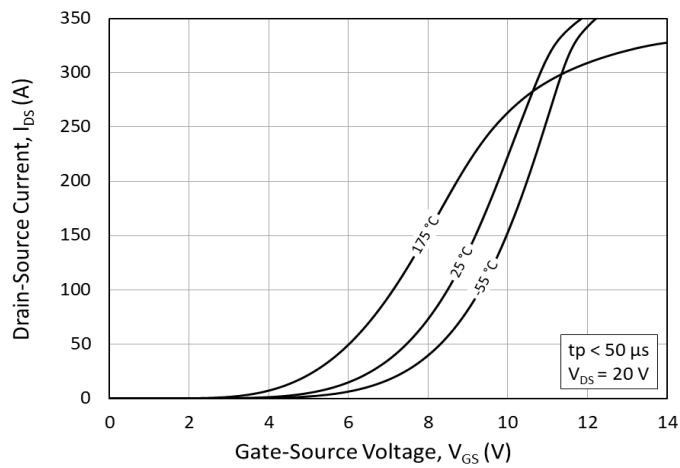
Figure 1. Output Characteristics  $T_{j} = -55^{\circ}\text{C}$ Figure 2. Output Characteristics  $T_{j} = 25^{\circ}\text{C}$ Figure 3. Output Characteristics  $T_{j} = 175^{\circ}\text{C}$ 

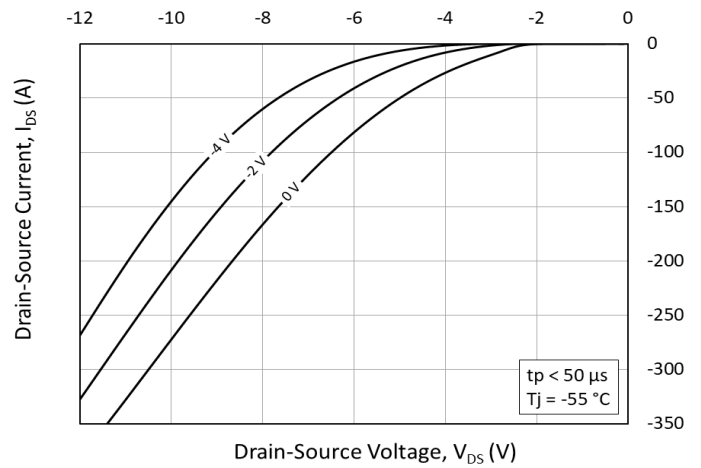
Figure 4. Normalized On-Resistance vs. Temperature

Figure 5. On-Resistance vs. Drain Current  
for Various TemperaturesFigure 6. On-Resistance vs. Temperature  
for Various Gate Voltages

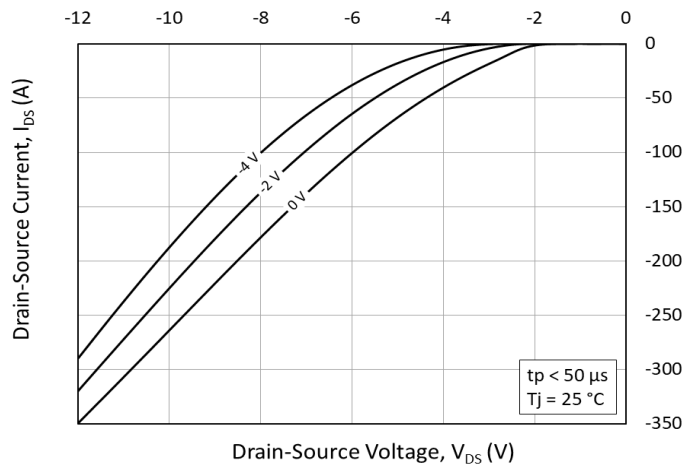
## Typical Performance



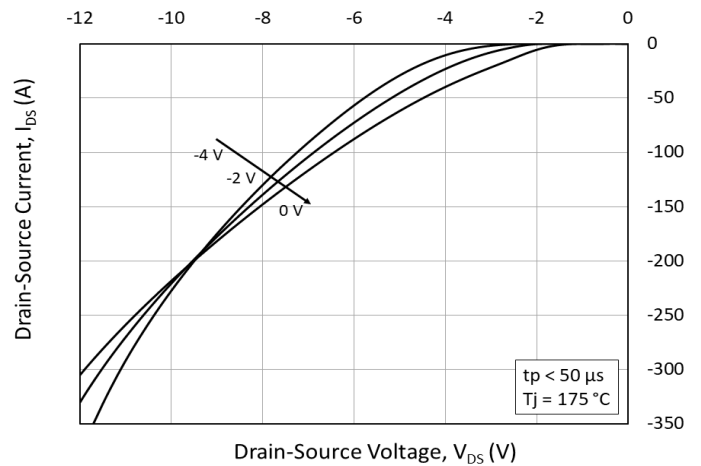
**Figure 7.** Transfer Characteristic for Various Junction Temperatures



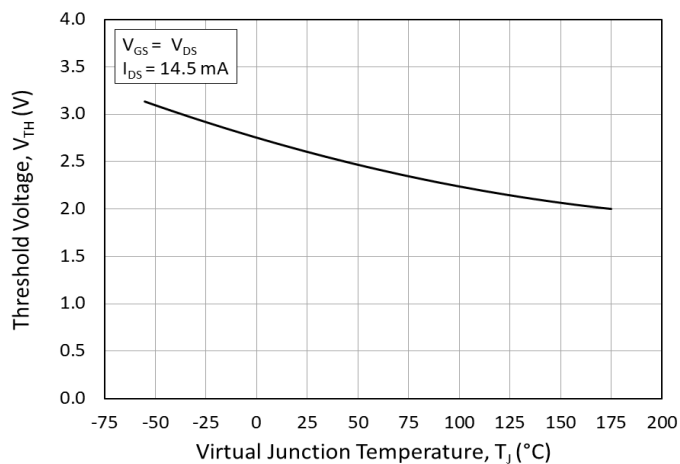
**Figure 8.** Body Diode Characteristic at  $T_J = -55\text{ }^{\circ}\text{C}$



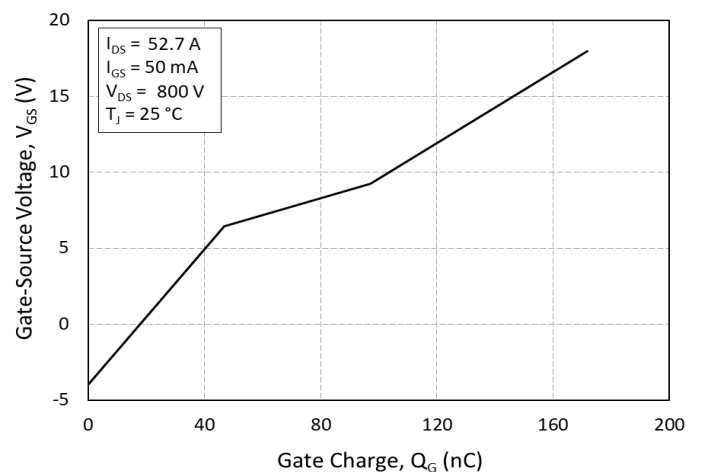
**Figure 9.** Body Diode Characteristic at  $T_J = 25\text{ }^{\circ}\text{C}$



**Figure 10.** Body Diode Characteristic at  $T_J = 175\text{ }^{\circ}\text{C}$



**Figure 11.** Threshold Voltage vs. Temperature



**Figure 12.** Gate Charge Characteristics

## Typical Performance

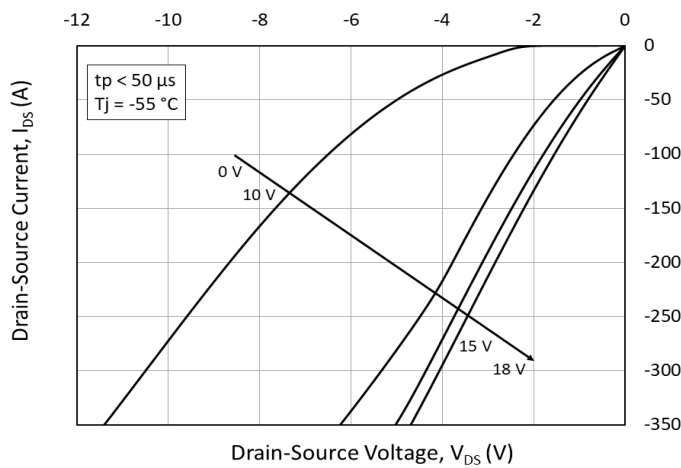
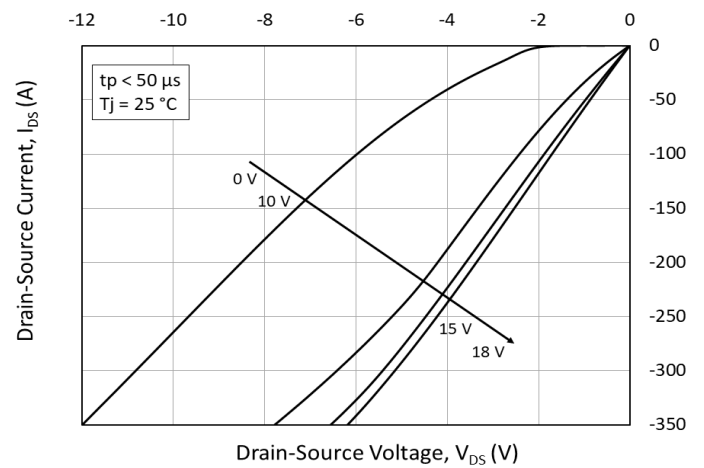
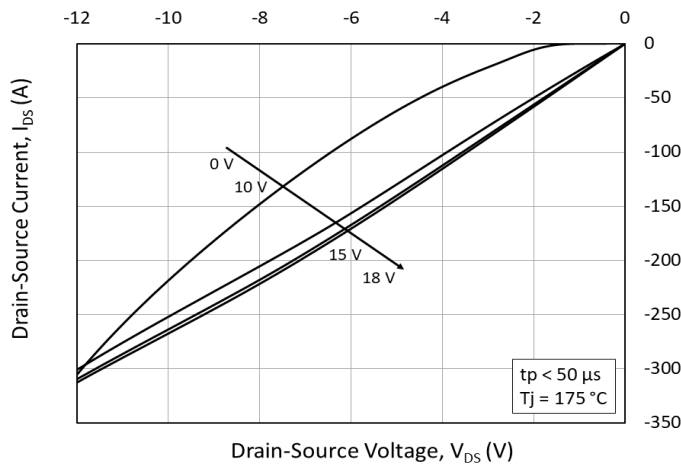
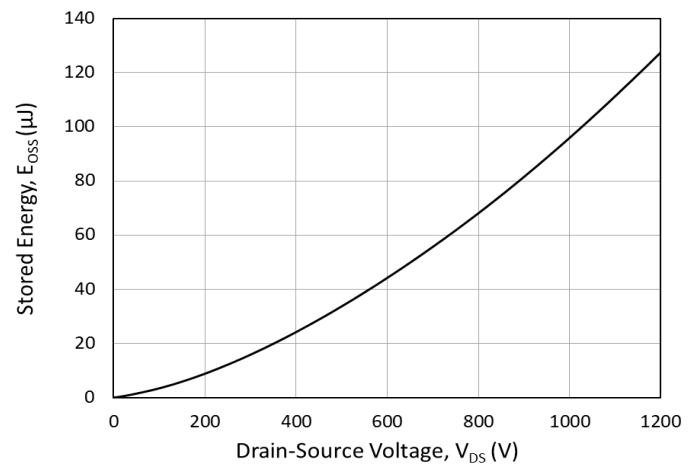
Figure 13. 3rd Quadrant Characteristic at  $T_J = -55\text{ }^{\circ}\text{C}$ Figure 14. 3rd Quadrant Characteristic at  $T_J = 25\text{ }^{\circ}\text{C}$ Figure 15. 3rd Quadrant Characteristic at  $T_J = 175\text{ }^{\circ}\text{C}$ 

Figure 16. Output Capacitor Stored Energy

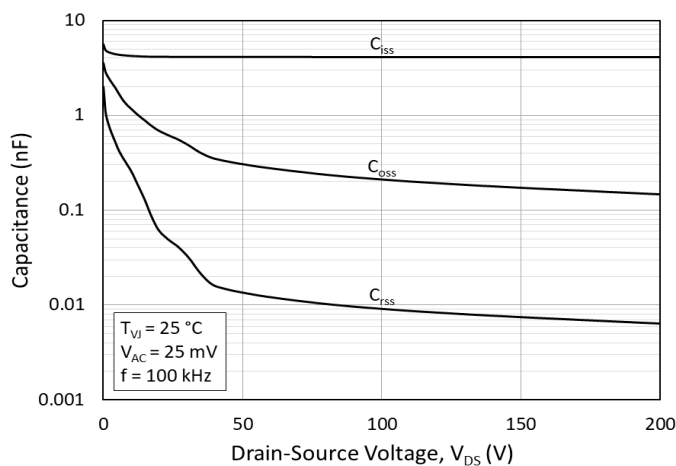


Figure 17. Capacitances vs. Drain-Source Voltage (0-200 V)

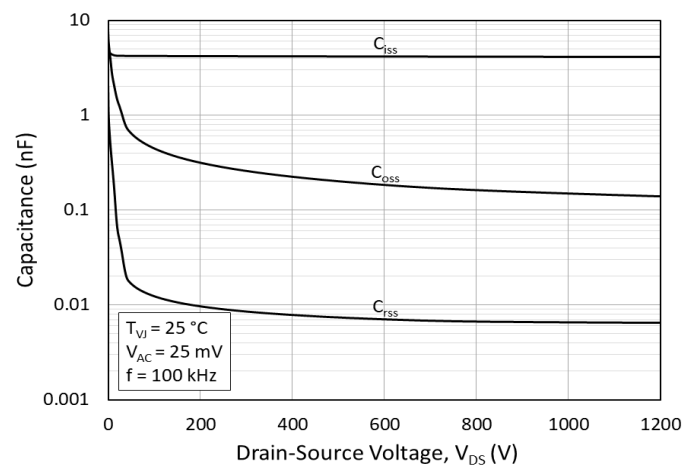
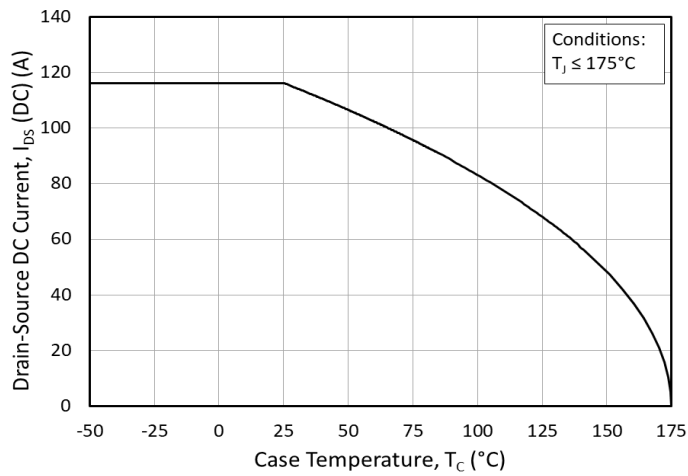
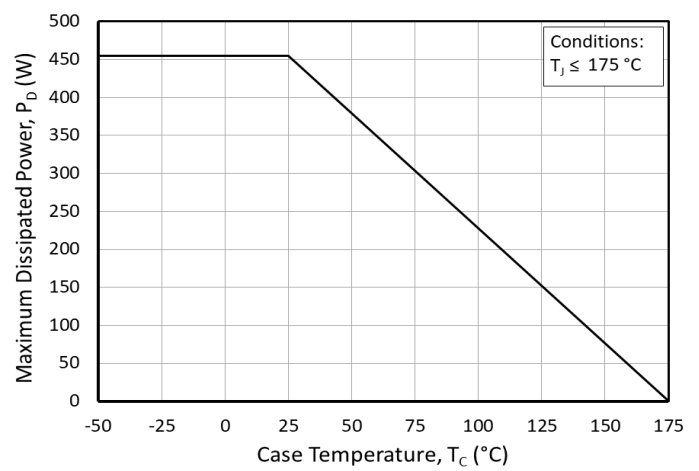


Figure 18. Capacitances vs. Drain-Source Voltage (0-1200 V)

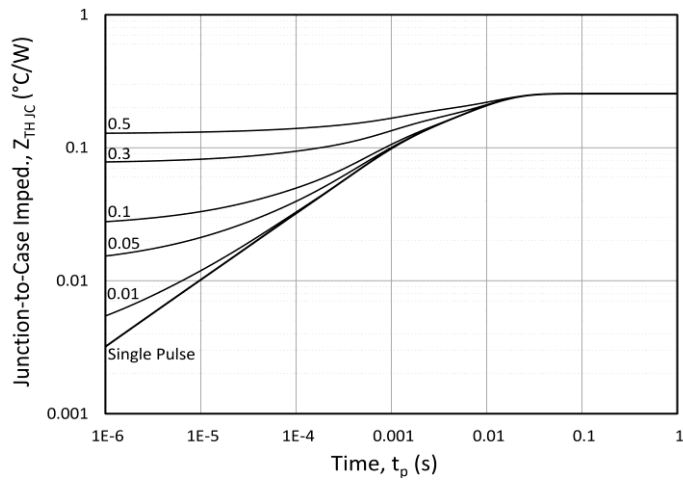
## Typical Performance



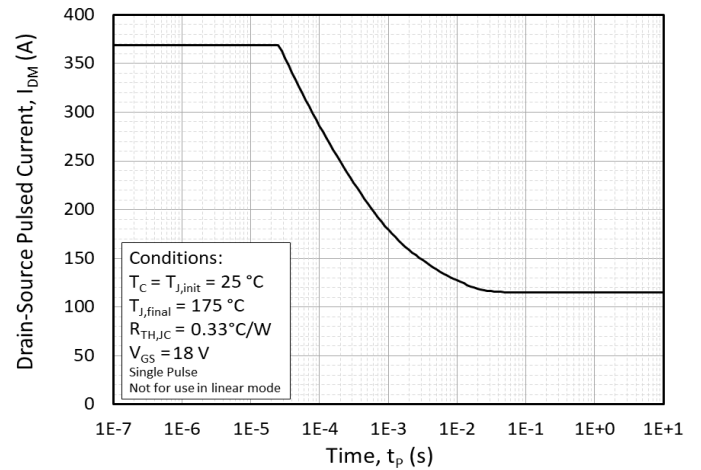
**Figure 19.** Continuous Drain Current Derating vs. Case Temperature



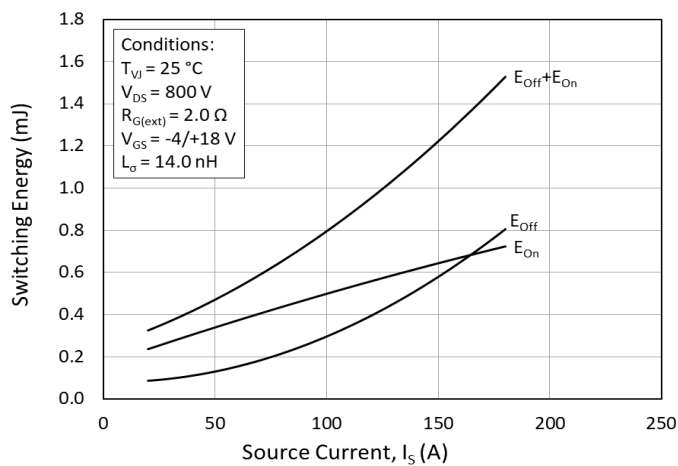
**Figure 20.** Maximum Power Dissipation Derating vs. Case Temperature



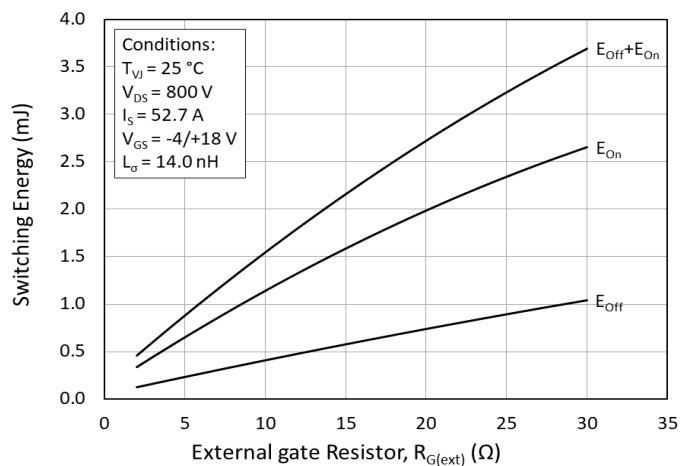
**Figure 21.** Transient Thermal Impedance (Junction - Case) °C/W



**Figure 22.** Safe Operating Area

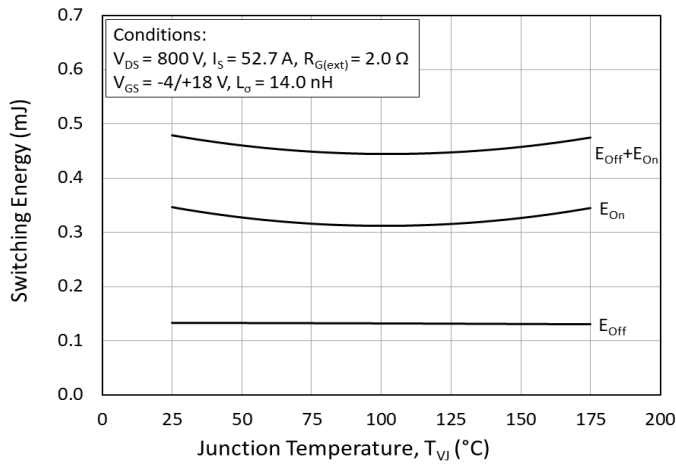


**Figure 23.** Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 800$  V)

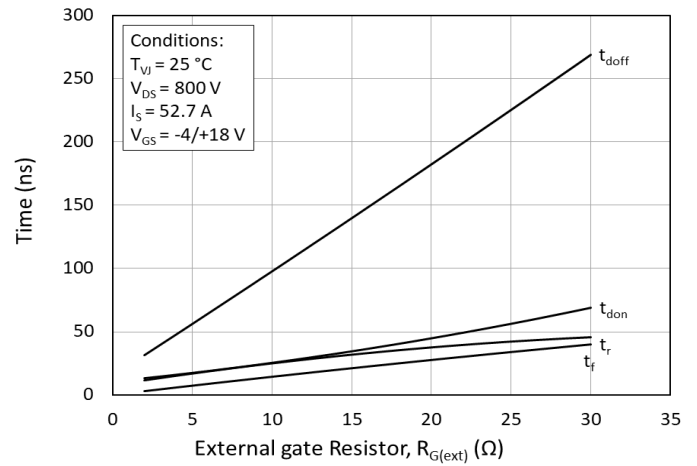


**Figure 24.** Clamped Inductive Switching Energy vs.  $R_{G(ext)}$

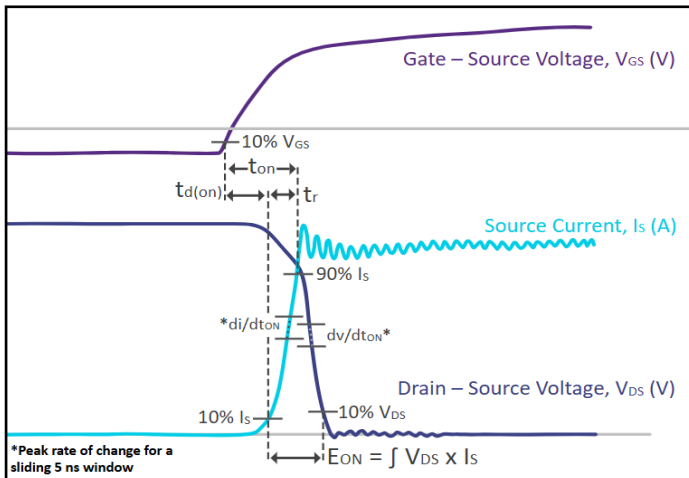
## Typical Performance



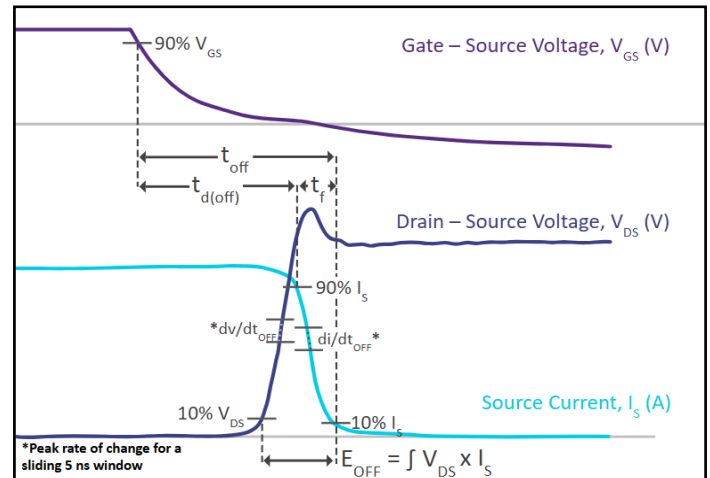
**Figure 25.** Clamped Inductive Switching Energy vs. Temperature



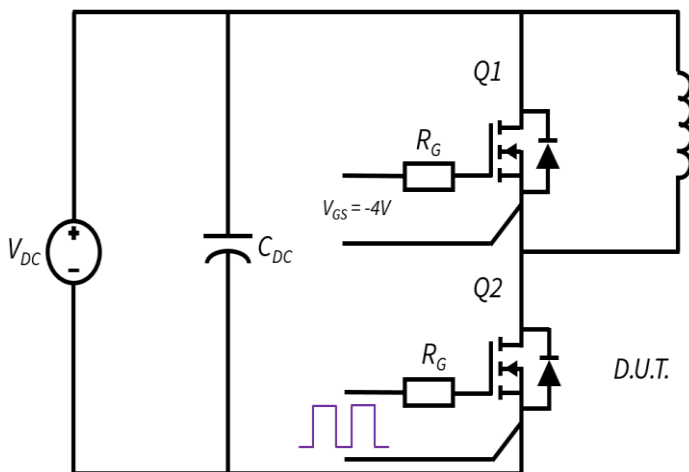
**Figure 26.** Switching Times vs.  $R_{G(ext)}$



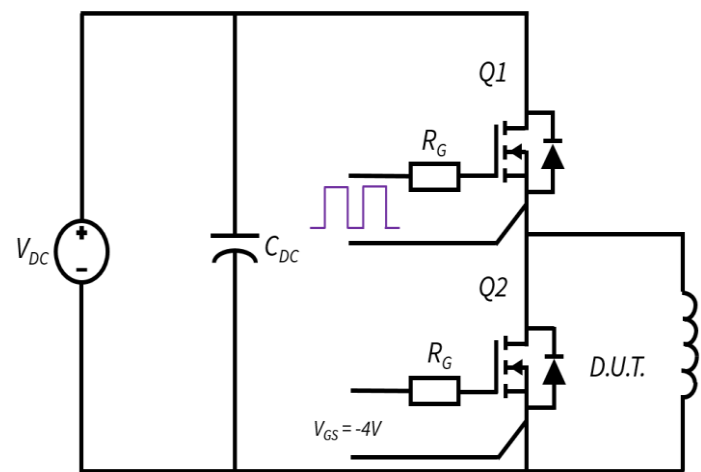
**Figure 27.** Turn On Switching Time Definition



**Figure 28.** Turn Off Switching Time Definition

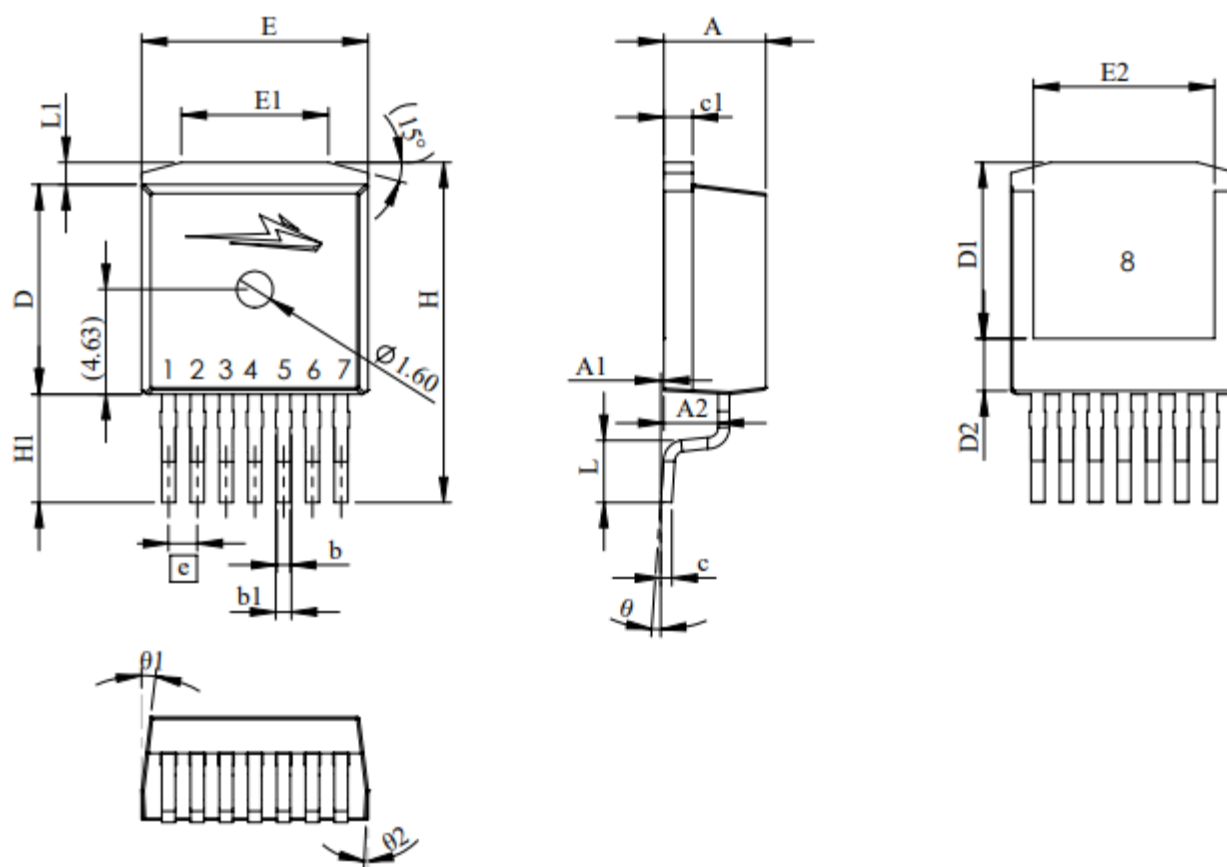


**Figure 29.** Clamped Inductive MOSFET Switching Waveform Test Circuit



**Figure 30.** Clamped Inductive Body Diode Switching Waveform Test Circuit

## Package Dimensions



| SYMBOL     | MIN (mm) | MAX (mm) |
|------------|----------|----------|
| A          | 4.30     | 4.70     |
| A1         | 0.00     | 0.25     |
| A2         | 2.20     | 2.60     |
| b          | 0.52     | 0.72     |
| b1         | 0.60     | 0.80     |
| c          | 0.42     | 0.62     |
| c1         | 1.07     | 1.47     |
| D          | 9.05     | 9.45     |
| D1         | 7.58     | 7.98     |
| D2         | 2.05     | 2.45     |
| E          | 9.80     | 10.20    |
| E1         | 6.30     | 6.97     |
| E2         | 7.80     | 8.20     |
| c          | 1.27 BSC |          |
| H          | 14.87    | 15.27    |
| H1         | 4.55     | 4.95     |
| L          | 2.48     | 2.88     |
| L1         | 0.87     | 1.27     |
| $\theta$   | 0°       | 8°       |
| $\theta$ 1 | 4°       | 10°      |
| $\theta$ 2 | 0°       | 6°       |

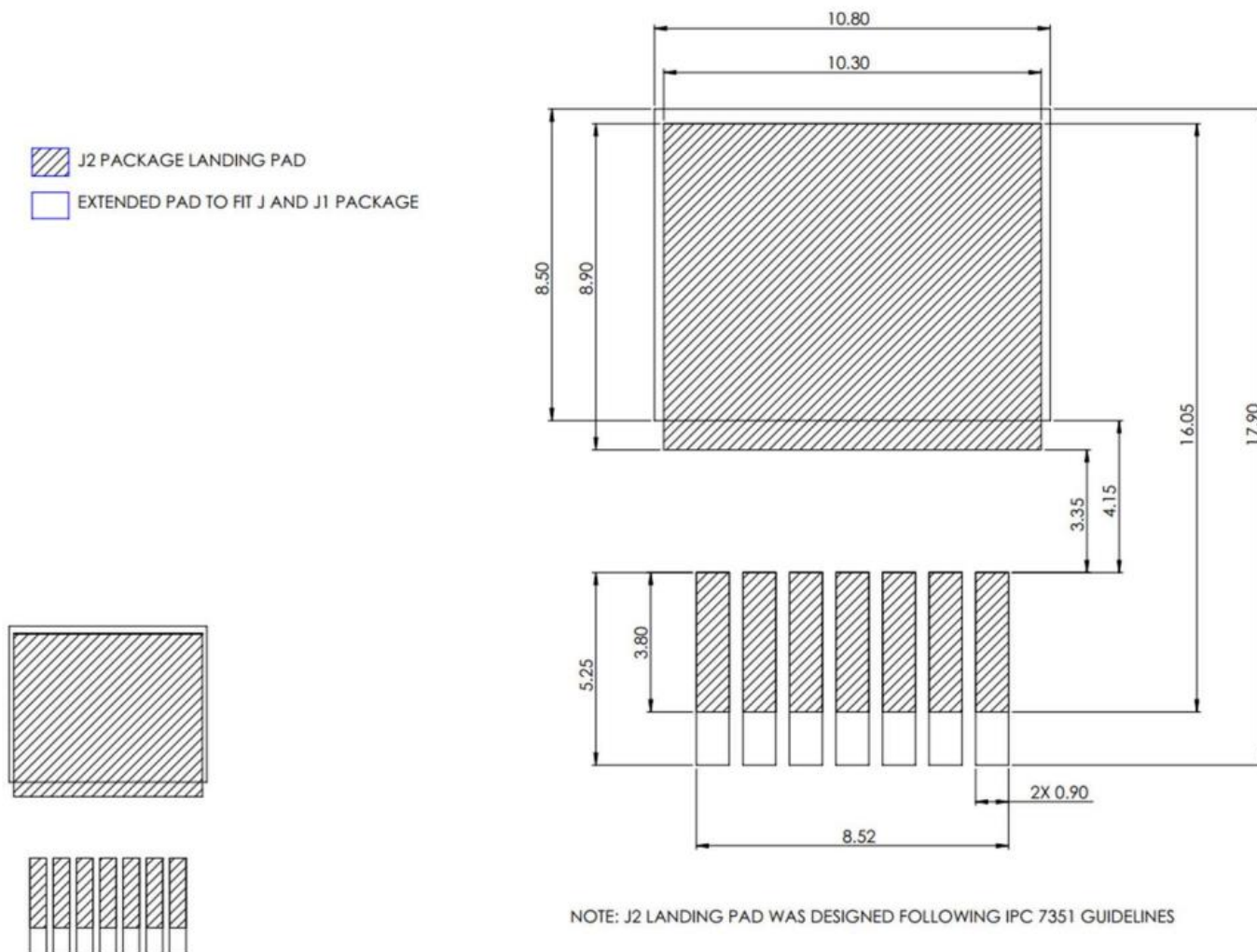
|   |        |
|---|--------|
| 1 | GATE   |
| 2 | KELVIN |
| 3 | SOURCE |
| 4 |        |
| 5 |        |
| 6 |        |
| 7 |        |
| 8 | DRAIN  |

### NOTE

1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
4. PACKAGE BURR FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS

## Recommended Solder Pad Layout

All dimensions in mm





## Revision History

| Documents Version | Date of Change | Description of Changes |
|-------------------|----------------|------------------------|
| 1                 | 6/10/2026      | Initial Release        |

## Appendix

| Appendix Number | Description                                                                                                                                                                                                                                                                                                                                                                |
|-----------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| A1              | <p>The following are recommendations for turning off the MOSFET with 0 V:</p> <ul style="list-style-type: none"><li>• Measure the <math>V_{GS}</math> spike accurately using high-CMRR probes and low common mode noise measurements.</li><li>• For the safe operation of the device, the voltage spike shall remain &lt; 5 V for a time duration of &lt; 40 ns.</li></ul> |



## Notes & Disclaimers

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